



Material Content Data Sheet



Sales Product Name		IPB80N08S4-06		Issued		25. January 2018		
MA#		MA001106272						
Package		PG-TO263-3-2		Weight*		1559.33 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	4.426	0.28	0.28	2839	2839
leadframe	inorganic material	phosphorus	7723-14-0	0.091	0.01		59	
	non noble metal	iron	7439-89-6	0.304	0.02		195	
	non noble metal	copper	7440-50-8	304.026	19.50	19.53	194971	195225
	non noble metal	aluminium	7429-90-5	5.820	0.37	0.37	3732	3732
wire	non noble metal	aluminium	7429-90-5	5.820	0.37	0.37	3732	3732
encapsulation	organic material	carbon black	1333-86-4	10.244	0.66		6570	
	plastics	epoxy resin	-	112.685	7.23		72265	
	inorganic material	silicondioxide	60676-86-0	560.011	35.91	43.80	359135	437970
leadfinish	non noble metal	tin	7440-31-5	9.657	0.62	0.62	6193	6193
plating	inorganic material	phosphorus	7723-14-0	0.001	0.00		1	
	non noble metal	nickel	7440-02-0	0.228	0.01	0.01	147	148
solder	non noble metal	tin	7440-31-5	0.069	0.00		44	
	noble metal	silver	7440-22-4	0.087	0.01		55	
	non noble metal	lead	7439-92-1	3.305	0.21	0.22	2120	2219
heatspreader	inorganic material	phosphorus	7723-14-0	0.165	0.01		105	
	non noble metal	iron	7439-89-6	0.548	0.04		352	
	non noble metal	copper	7440-50-8	547.666	35.12	35.17	351217	351674
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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